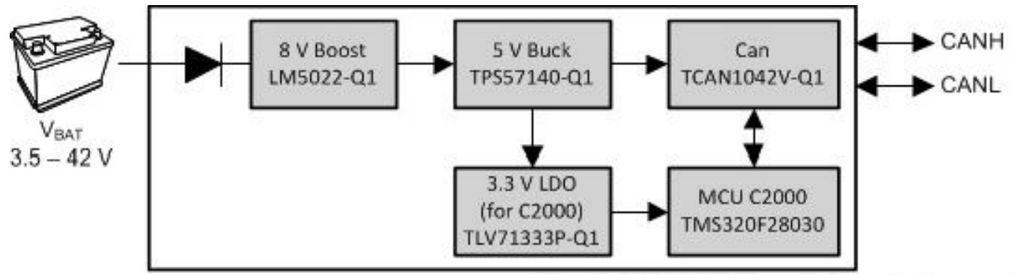
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



Orderable: N/A	Designed for: Public Release	Mod. Date: 7/7/2017
TID #: TIDA-01429	Project Title: Discrete SBC Boost Buck	
Number: TIDA-01429 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 4
Drawn By:	File: TIDA-01429_Boost_Buck_CoverSheet.SchDoc	Size: B
Engineer: John Griffith	Contact: http://www.ti.com/support	

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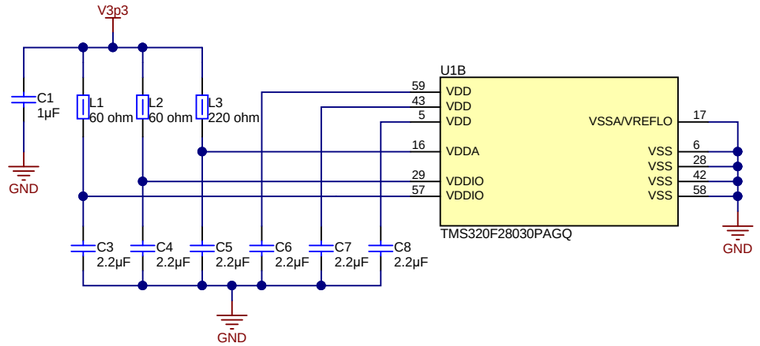
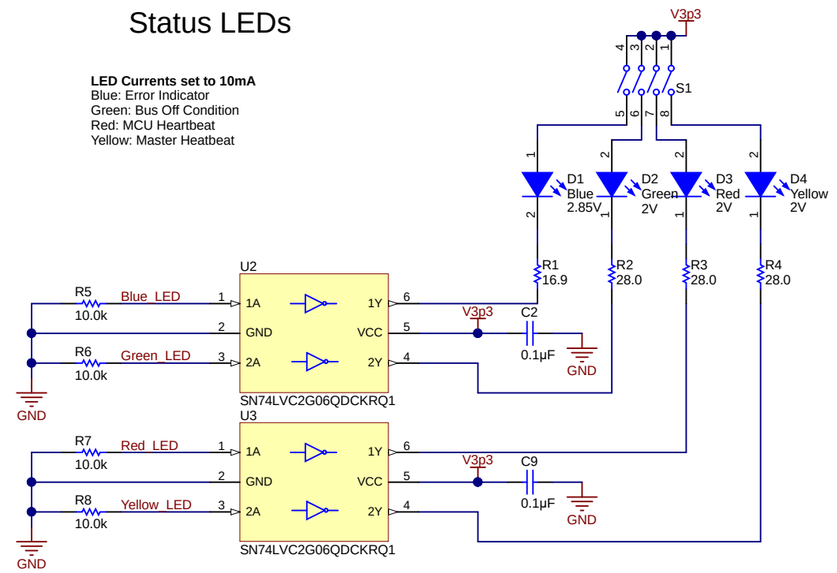
C2000 Power Connections - TMS320F29030Q



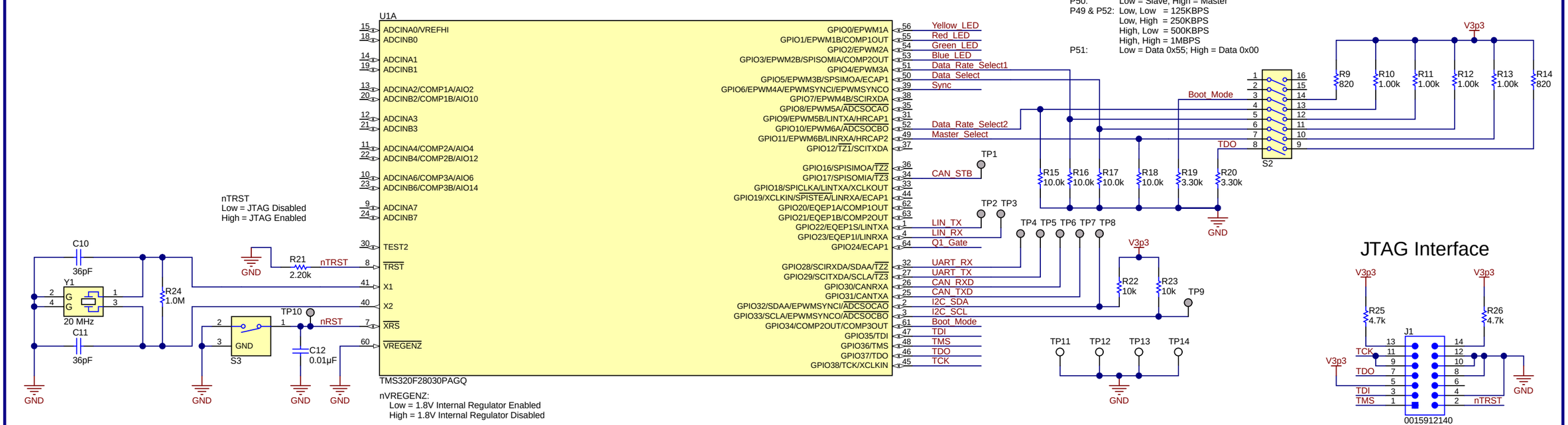
Place capacitors as close to VDD pins as possible

Status LEDs

LED Currents set to 10mA
Blue: Error Indicator
Green: Bus Off Condition
Red: MCU Heartbeat
Yellow: Master Heatbeat



C2000 Peripheral Connections - TMS320F28030Q



Mode Selection DIP Switches

Resistor Selection
P50: Low = Slave; High = Master
P49 & P52: Low, Low = 125KBPS
Low, High = 250KBPS
High, Low = 500KBPS
High, High = 1MBPS
P51: Low = Data 0x55; High = Data 0x00

JTAG Interface

Orderable: N/A	Designed for: Public Release	Mod. Date: 6/22/2017
TID #: TIDA-01429	Project Title: Discrete SBC Boost Buck	
Number: TIDA-01429 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 4
Drawn By:	File: TIDA-01429_Boost_Buck_MCU.SchDoc	Size: B
Engineer: John Griffith	Contact: http://www.ti.com/support	

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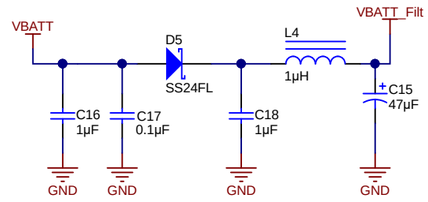
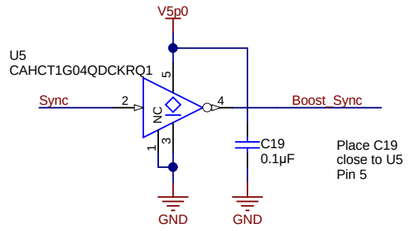
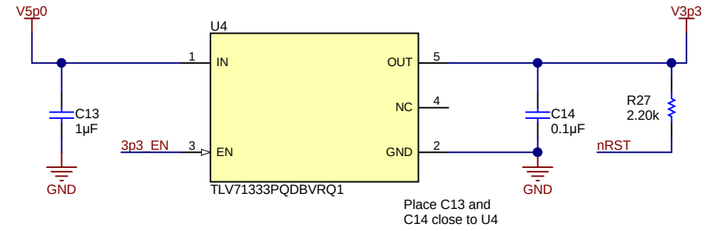
Reverse Battery Protection and Conducted Emissions Filter



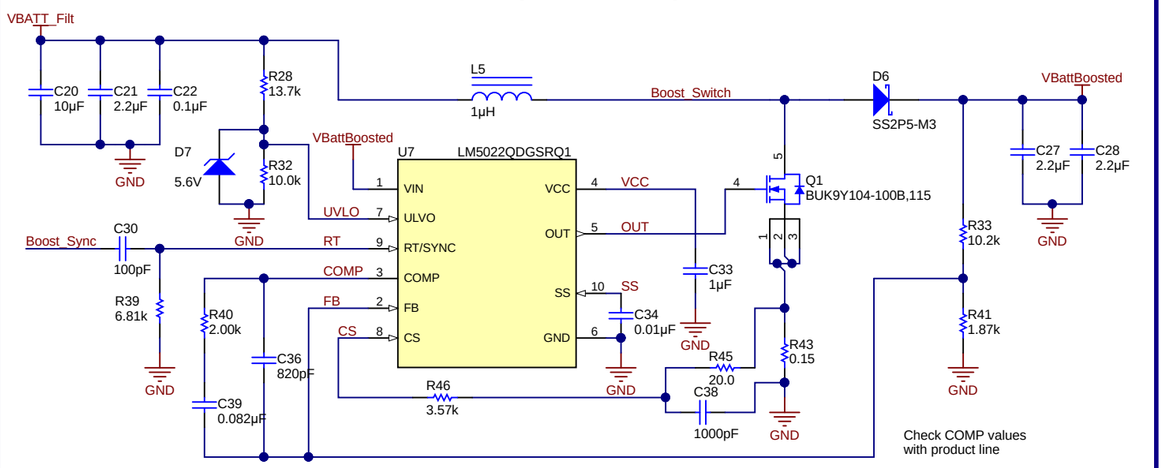
Level Shifting Sync Clock for Boost



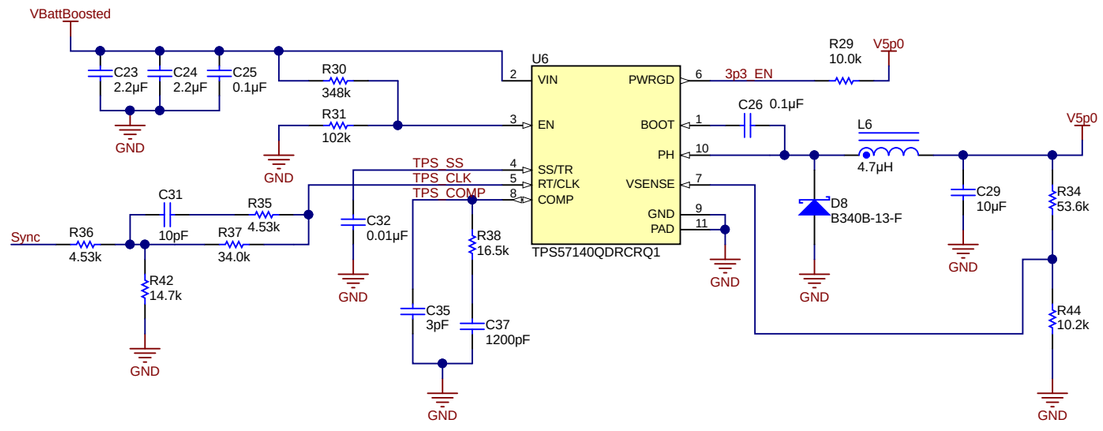
3.3V 150mA LDO for C2000



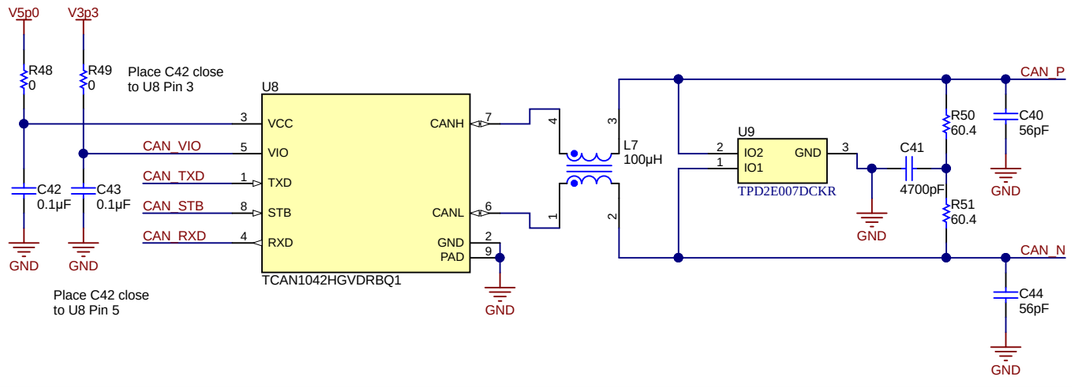
Automotive, 65V Wide VIN, adjustable, Asynchronous Boost Controller



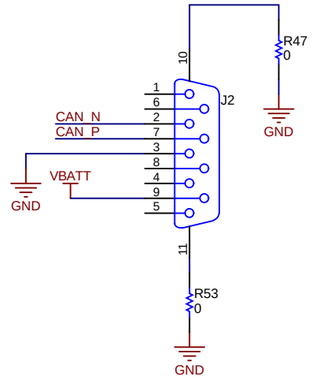
Automotive, 42V Wide VIN, adjustable, 1.5 Amp, Asynchronous Buck Converter



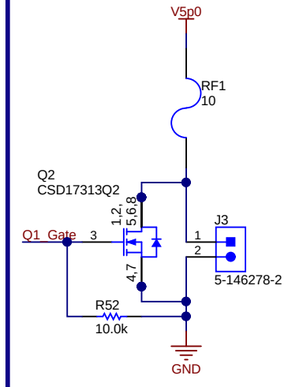
5MBPS CAN FD Transceiver with I/O Level Shifting in DFN Package



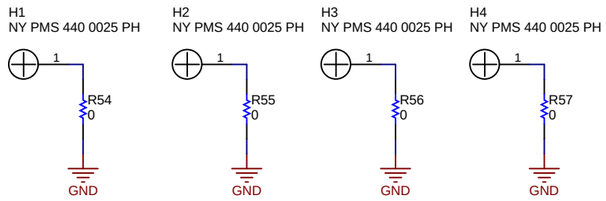
External Connector - Female, 9-Pin, DSUB, R/A



Load Resistor



Orderable: N/A		Designed for: Public Release	Mod. Date: 6/23/2017
TID #: TIDA-01429		Project Title: Discrete SBC Boost Buck	
Number: TIDA-01429	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 3 of 4
Drawn By:		File: TIDA-01429_Boost_Buck_Main.SchDoc	Size: B
Engineer: John Griffith		Contact: http://www.ti.com/support	



PCB Number: TIDA-01429
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

Variant/Label Table	
Variant	Label Text
001	Standard Build

LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 6/22/2017
TID #: TIDA-01429	Project Title: Discrete SBC Boost Buck	
Number: TIDA-01429 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 4 of 4
Drawn By:	File: TIDA-01429_Boost_Buck_Hardware.SchDoc	Size: B
Engineer: John Griffith	Contact: http://www.ti.com/support	

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